Material Declaration Report

Package Type:	**SC70-3**
Pericom Package Code:	**C03 (Pb-free)**
RoHS Compliance:	**Yes**
Applicable Exemption:	**N/A**

Component Weight (mg):	**6.254**
Termination Plating:	**Matte Tin**
JESD 97 Pb-free Category:	**e3**
Plating Thickness (um):	**7~17**
Tin Whisker Mitigation:	**Anneal, 150C/1.5hr**

MSL Rating:	**1**
Peak Body Temp (C):	**260**
Max Time (sec):	**10**
Reflow Cycles:	**3**
Rev Date:	**Mar.27.2012**

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	3.535	CJE	Silica, vitreous	60676-86-0	80.000	2.828
			Silicon dioxide	7631-86-9	17.000	0.601
			Boron zinc hydroxide oxide (B12Zn4(OH)14O15)	138265-88-0	1.000	0.035
			Phenol-formaldehyde polymer	9003-35-4	1.000	0.035
			Carbon black	1333-86-4	1.000	0.035
LEAD FRAME	1.850		Nickel	7440-02-0	41.000	0.759
			Manganese	7439-96-5	0.800	0.015
			Cobalt	7440-48-4	0.500	0.009
			Silicon	7440-21-3	0.300	0.006
			Phosphorus	7723-14-0	0.025	0.000
			Sulfur	7704-34-9	0.025	0.000
			Carbon	7440-44-0	0.050	0.001
			Iron	7439-89-6	57.290	1.060
			Silver	7440-22-4	0.010	0.000
TERMINATION PLATING	0.1400		Tin	7440-31-5	99.90	0.13986
			Impurity	Proprietary	0.10	0.00014
SILICON DIE	0.350		Silicon	7440-21-3	99.763	0.34917
			Aluminum(Al)	7429-90-5	0.200	0.00070
			Copper(Cu)	7440-50-8	0.001	0.00000
			Titanium(Ti)	7440-32-6	0.028	0.00010
			Phosphorus(P)	7664-38-2	0.003	0.00001
			Boron(B)	7440-42-8	0.005	0.00002
DIE ATTACH EPOXY	0.350		Silica, crystalline	14808-60-7	42.500	0.14875
			Epoxy resin	Secret	25.000	0.08750
			Epoxy resin	Secret	15.000	0.05250
			Epoxy resin modifier	Secret	15.000	0.05250
			Amine	Secret	2.500	0.00875
GOLD WIRE	0.029		Au	7440-57-5	99.99	0.0289971
			Other materials	Secret	0.01	0.0000029

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

	MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Device	Mold Compound	<2	<2	<2	<2	<5	<5
	Leadframe	<50	<2	<2	<2	<5	<5
	Silicon Die	<2	<2	<2	<2	<5	<5
	Die Attach Epoxy	<2	<2	<2	<2	<5	<5
	Gold Wire	<2	<2	<2	<2	<5	<5
	Solder Plating	<2	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC

and

China RoHS Directive SJ/T11363-2006

Declaration Statement: Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium

Pb <1000ppm	Hg <1000ppm	Cr+6 <1000ppm	Cd <100ppm	PBB <1000ppm	PBDE <1000ppm
O	O	O	O	O	O

O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.
X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.